

a' solder balls 160 may have a pitch of 1.27 millimeters, 1.0 millimeters, 0.80 millimeters, 0.75 millimeters, or any other pitch suitable for a desired application. It will be appreciated that solder balls may be added at other suitable times during the manufacturing process.

Please replace the paragraph beginning on page 5, line 10 with the following:

a2 FIG. 6 illustrates a heat sink 150 added on top of unpackaged semiconductor die 110 and packaged die 120 and 130 to aid in removing heat from the circuits. As illustrated, the distance "d" from the top of multi-die module substrate 140 to the top of packaged die 120 and 130 is substantially equal to the distance from the top of multi-die module substrate 140 to the top of the encapsulation material over unpackaged semiconductor die 110, which is referred to herein as the top of unpackaged semiconductor die 110. In at least one embodiment, distance "d" is about 1.3 millimeters. Making these distances the same facilitates effective use of heat sink 150, although heat sink 150 could be fabricated to account for any difference between the heights of various packaged and/or unpackaged die attached or mounted to multi-die module substrate 140. In various embodiments, heat sink 150 may be a thin strip of heat conductive material, a large heat sink with fins for added heat dissipation, or any other suitable type of heat sink.

Please replace the paragraph beginning on page 6, line 7 with the following:

a3 FIG. 9 shows packaged die 120 and 130 attached as already discussed. Note however, that the top of unpackaged semiconductor die 111 is not level with the tops of packaged die 120 and 130. Therefore, shim 190 is used to effectively raise the top of unpackaged die 111 to be even with the tops of packaged die 120 and 130, and thereby facilitate the use of a heat sink (not shown). Shim 190 may be composed of silicon, or another suitable heat conveying material. It will be appreciated that a shim such as shim 190 may be used on top of packaged die 120 and/or 130, instead of or in addition being used on top of unpackaged die 111 if needed.

IN THE CLAIMS

Please amend claims 6-7 and 9 to read as shown below by substituting the below claims for claims having the same number, and add claims 41-55 as follows. Pursuant to 37 C.F.R. §1.121, a marked-up version of the following claims is provided at the end of this Amendment as Exhibit C.